

Ring Remover

mRR 200



Description

The Ring Remover mRR 200 enables fully automated removal of rings from laminated 200 mm (8") wafers on film frames.

Application

- automated ring removing

Features

- optimized footprint
- throughput of up to 80 wafers on film frames per hour
- Cleanroom class: ISO class 6
- CE certificated
- SEMI standard compliant

Basic Configuration

- one dual-arm robot
- two frame end-effectors 8"
- two cassette ports for 200 mm (8") wafers on film frames
- two ring remover stations 8"
- wafer flipping function
- GUI

Configuration Options

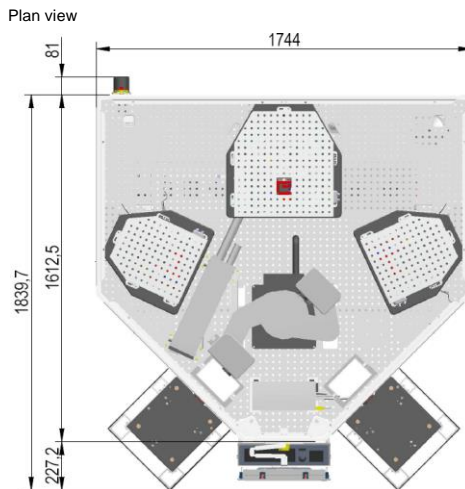
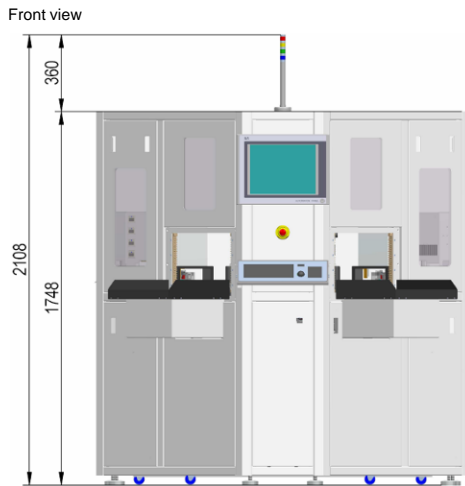
- OCR reader for frame ID
- RFID for frame cassettes
- barcode reader for frame ID
- SECS/GEM interface
- FFU (filter fan unit) for higher cleanroom class
- UPS (uninterruptible power supply)
- ionizer

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Specifications



Frame size	For 200 mm (8") wafers or optional 300 mm (12") wafers
Cleanroom class*	ISO class 6
Dimensions	
w / d / h in mm	1744 / 1920 / 2108
Service area	600 mm around the machine
Weight	About 1000 kg
Operation and loading	
Operation and loading	From each side
Cassette loading	Manual
Shipping box loading	Manual
End-effector change	Manual
Supply	
Power supply	200-240 VAC / 50-60 Hz / 20 A
Control voltage	24 VDC
Pneumatic	
Pneumatic media	CDA and N ₂
Supply pressure CDA	6.0 – 7.0 bar
Supply pressure N ₂	6.0 – 7.0 bar
Interface	
Operator interface	Monitor + keyboard (opt. touch screen)
External interface	USB, Ethernet, SECS/GEM (optional)
Service Interface	Remote control (optional)
Throughput	
Throughput (depends on recipe)	Up to 80 wafer film frames per hour
CE certificates	2006/95/EC, 2006/42/EC, 2004/108/EC
SEMI standards compliant	

* ISO EN 14 644-1

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